



DESCRIPTION

EC-861 is a phenyl acetate epoxy curative. When cured with an epoxy, the resulting thermoset displays a high level of toughness and flexibility. The monomer is hydrophobic by nature and results in more hydrophobic thermosets. The low viscosity makes it an ideal monomer to formulate in epoxy resin systems. The phenyl acetate end group, unlike phenolics, does not interfere with free-radical cure in hybrid adhesive systems.

HIGHLIGHTS

• Low modulus	• Hydrophobic
• Toughener	• Thermal stability
• Hydrolytically resistant thermosets	• Does not impede free-radical cure

TYPICAL PHYSICAL AND CHEMICAL PROPERTIES

PROPERTY	METHOD	RESULT
Appearance at Room Temperature	Visual	Yellow liquid
Viscosity at 25°C (typical)	Haake Rheometer	3,000 cps
Functionality		2
Molecular Weight		861
Onset of Decomposition	TGA	> 350°C
Recommended Storage Temp		25°C or below

Data is for reference only and may vary depending on testing method used. The structure shown above is an idealized representation of a statistical distribution.

RECOMMENDED FORMULATION USE:

EC-861 is recommended for use as an epoxy curative for systems requiring a high level of toughness, hydrophobicity, and low modulus. EC-861 curative should be used in conjunction with multifunctional epoxies or in the presence of about a 20% excess of difunctional epoxies if a thermoset is desired.

Formulations containing approximately one-to-one equivalent levels with difunctional epoxies can result in tough thermoplastics. Standard epoxy catalysts such as amines, imidizoles, and Lewis acids work well to cure EC-861 with epoxy resins.

CONTACT:

REQUEST A SAMPLE OR PLACE AN ORDER

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REF: DMI Part Number: R1165